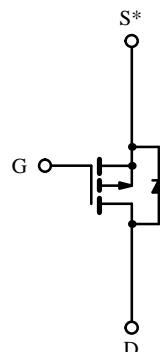
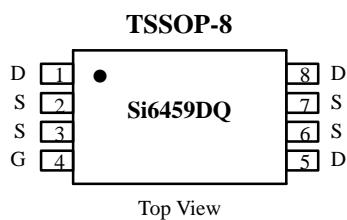


P-Channel Enhancement-Mode MOSFET

Product Summary

V _{DS} (V)	r _{Ds(on)} (Ω)	I _D (A)
-60	0.120 @ V _{GS} = -10 V	TRENCHFET™ POWER MOSFETS ± 2.4
	0.150 @ V _{GS} = -4.5 V	



*Source Pins 2, 3, 6 and 7 must be tied common.

P-Channel MOSFET

Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-60	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current (T _J = 150°C) ^a	I _D	± 2.6	A
		± 2.1	
Pulsed Drain Current	I _{DM}	± 30	
Continuous Source Current (Diode Conduction) ^a	I _S	-1.25	
Maximum Power Dissipation ^a	P _D	1.5	W
		1.0	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Ambient ^a	R _{thJA}	83	°C/W

Notes

a. Surface Mounted on FR4 Board, t ≤ 10 sec.

Subsequent updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #1819.

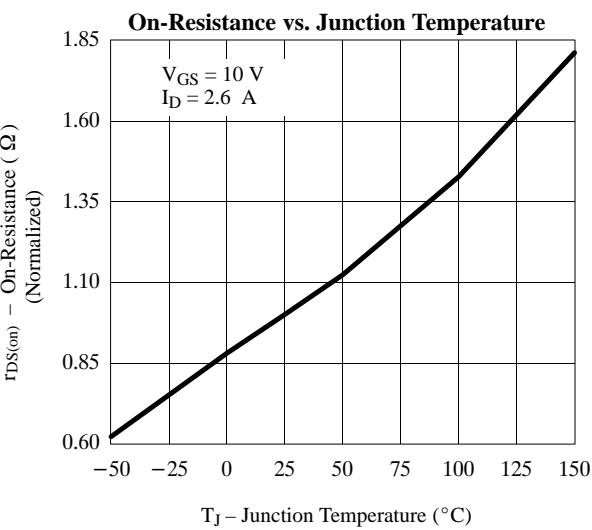
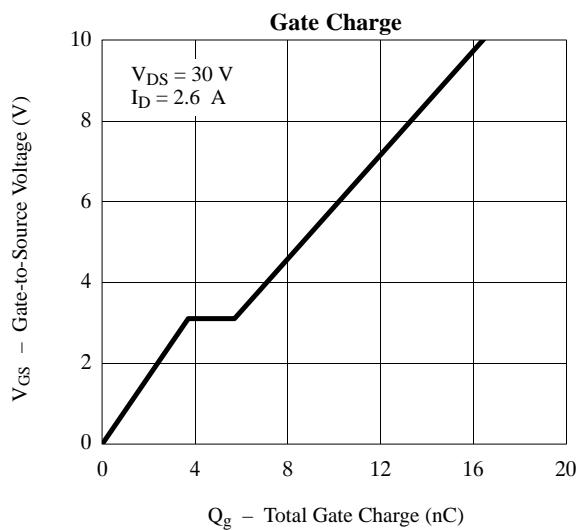
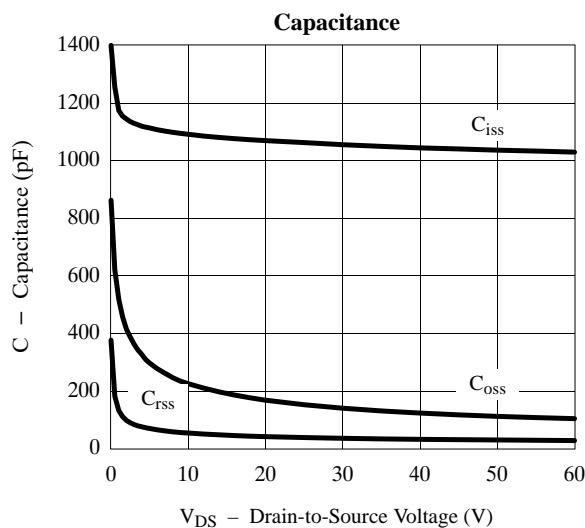
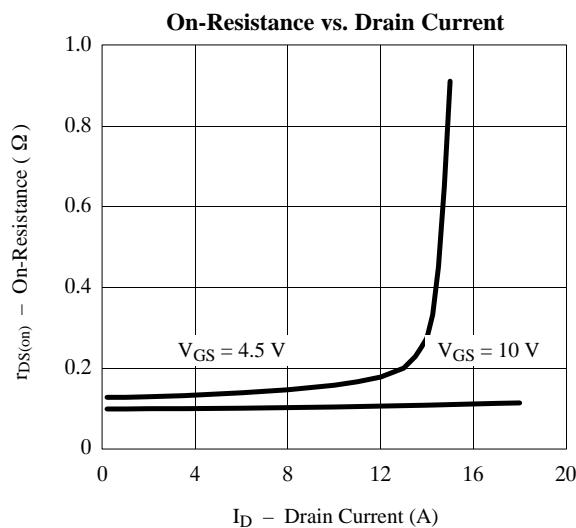
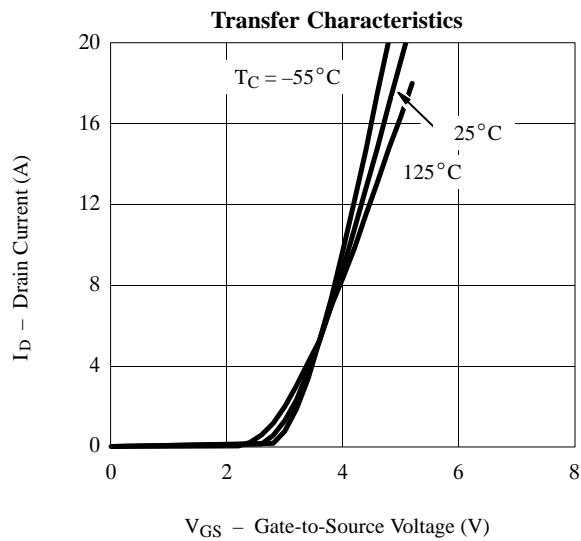
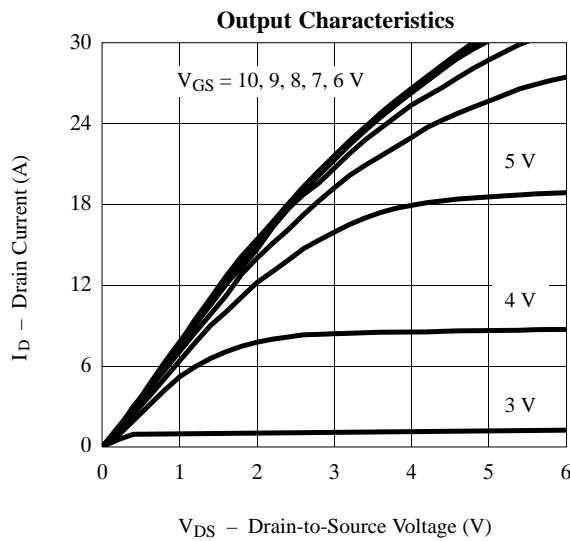
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-1.0			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$		-1		μA
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 70^\circ\text{C}$		-25		
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	-20			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}, I_D = -2.6 \text{ A}$		0.100	0.120	Ω
		$V_{GS} = -4.5 \text{ V}, I_D = -2.4 \text{ A}$		0.125	0.150	
Forward Transconductance ^a	g_f	$V_{DS} = -15 \text{ V}, I_D = -2.6 \text{ A}$		7.5		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -1.25 \text{ A}, V_{GS} = 0 \text{ V}$		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -2.6 \text{ A}$		16	25	nC
Gate-Source Charge	Q_{gs}			3.7		
Gate-Drain Charge	Q_{gd}			2.0		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -30 \text{ V}, R_L = 30 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6 \Omega$		8	15	ns
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(\text{off})}$			12	25	
Fall Time	t_f			35	50	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -1.25 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		60	90	

Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

Typical Characteristics (25°C Unless Noted)



Typical Characteristics (25°C Unless Noted)

